



- High frequency operation
- High purity, high temperature epoxy encapsulation for enhanced mechanical strength and moisture resistance
- Guard ring for enhanced ruggedness and long term reliability
- Solder dip 275 °C max. 7 s, per JESD 22-B106

Typical applications are in switching power supplies, converters, freewheeling diodes, and reverse battery protection.

- : TO-220AB
Molding compound meets



$T_a=25$ Unless otherwise specified

Thermal Resistance	Between junction and case	R θ J-C	/W	2.0

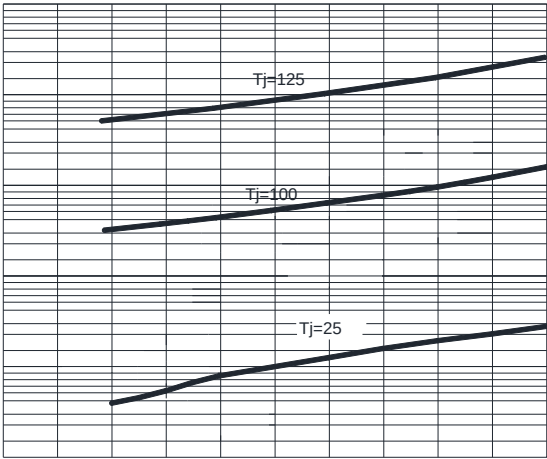


(Example)

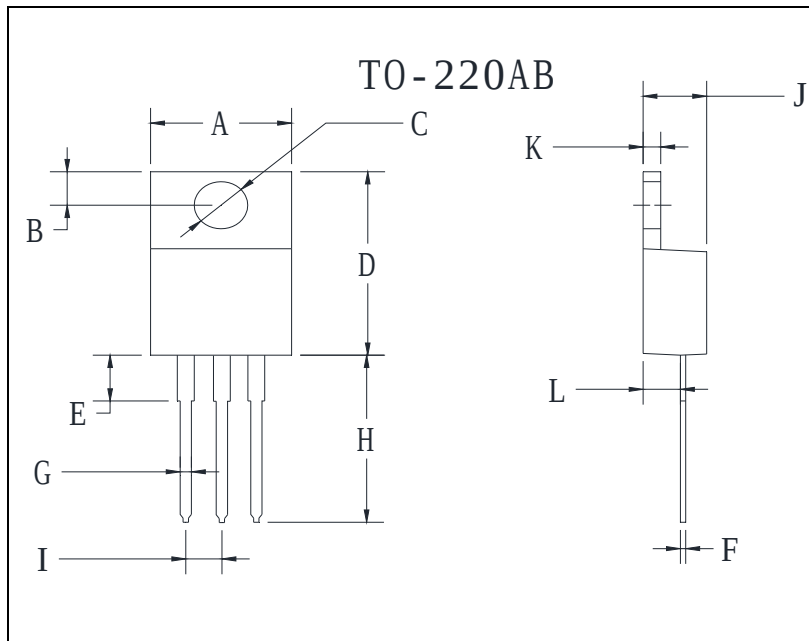
MBR2060CTS	Approximate 1.9	50	1000	5000	Tube



(Typical)



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Dim	Min	Max
A	9.95	10.35
B	2.55	2.95
C	3.8	4.0
D	14.95	15.25
E	3.75	4.25
F	0.26	0.5
G	0.68	0.94
H	13.4	13.9
I	2.35	2.65
J	4.38	4.78
K	1.14	1.4
L	2.37	2.79

